

# N-Channel 60-V (D-S) MOSFET

| PRODUCT SUMMARY          |                                  |                    |                      |  |
|--------------------------|----------------------------------|--------------------|----------------------|--|
| V <sub>(BR)DSS</sub> (V) | $r_{DS(on)}(\Omega)$             | I <sub>D</sub> (A) | Q <sub>g</sub> (Typ) |  |
| 60                       | 0.0055 at V <sub>GS</sub> = 10 V | 90 <sup>d</sup>    | 78.5                 |  |

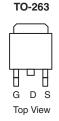
#### **FEATURES**

- TrenchFET® Power MOSFETS
- 175 °C Junction Temperature
- 100 % R<sub>q</sub> and UIS Tested

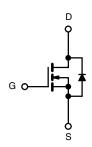


#### **APPLICATIONS**

- Power Supply
  - Secondary Synchronous Rectification
- Industrial



Ordering Information: SUM90N06-5m5P-E3 (Lead (Pb)-free)



N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b>                     | T <sub>C</sub> = 25 °C, unless oth  | erwise noted                      |                  |      |  |
|---|-------------------------------------|-----------------------------------|------------------|------|--|
| Parameter   | Symbol                              | Limit                             | Unit             |      |  |
| Drain-Source Voltage                                |                                     | V <sub>DS</sub>                   | 60               | V    |  |
| Gate-Source Voltage                                 |                                     | V <sub>GS</sub>                   | ± 20             |      |  |
| Continuous Drain Current (T <sub>.I</sub> = 175 °C) | T <sub>C</sub> = 25 °C              | 1-                                | 90 <sup>d</sup>  |      |  |
| Continuous Diam Current (1j = 175 C)                | T <sub>C</sub> = 70 °C              | I <sub>D</sub>                    | 90 <sup>d</sup>  |      |  |
| Pulsed Drain Current                                |                                     | I <sub>DM</sub>                   | 240              | - A  |  |
| Avalanche Current                                   |                                     | I <sub>AS</sub>                   | 50               |      |  |
| Single Avalanche Energy <sup>a</sup>                | L = 0.1 mH                          | E <sub>AS</sub>                   | 125              | mJ   |  |
| Maximum Power Dissipation <sup>a</sup>              | T <sub>C</sub> = 25 °C              | В                                 | 272 <sup>b</sup> | w    |  |
|   | T <sub>A</sub> = 25 °C <sup>c</sup> | $ P_D$ $-$                        | 3.75             | ] vv |  |
| Operating Junction and Storage Temperature Range    |                                     | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175      | °C   |  |

| THERMAL RESISTANCE RATINGS                   |                   |       |         |  |
|--|-------------------|-------|---------|--|
| Parameter                                    | Symbol            | Limit | Unit    |  |
| Junction-to-Ambient (PCB Mount) <sup>c</sup> | R <sub>thJA</sub> | 40    | °C/W    |  |
| Junction-to-Case (Drain)                     | R <sub>thJC</sub> | 0.55  | - 'C/VV |  |

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).
- d. Package limited.

# SUM90N06-5m5P

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| Parameter                                     | Symbol                      | Test Conditions  | Min | Тур    | Max    | Unit |
|---|-----------------------------|--|-----|--------|--------|------|
| Static  |                             |  |     |        |        |      |
| Drain-Source Breakdown Voltage                | V <sub>(BR)DSS</sub>        | $V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$  | 60  |        |        | V 5  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub>         | $V_{DS} = V_{GS}, I_D = 250 \mu A$   | 2.5 |        | 4.5    |      |
| Gate-Body Leakage                             | I <sub>GSS</sub>            | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$  |     |        | ± 250  | nA   |
| Zero Gate Voltage Drain Current               |                             | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V  |     |        | 1      |      |
|   | I <sub>DSS</sub>            | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C                         |     |        | 50     | μА   |
|   |                             | V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C                         |     |        | 250    |      |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>          | $V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$   | 70  |        |        | Α    |
|   | _                           | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A  |     | 0.0045 | 0.0055 | Ω    |
| Drain-Source On-State Resistance <sup>a</sup> | r <sub>DS(on)</sub>         | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C                         |     | 0.0072 | 0.009  |      |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>             | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A  |     | 58     |        | S    |
| Dynamic <sup>b</sup>                          |                             |  |     | •      |        |      |
| Input Capacitance                             | C <sub>iss</sub>            | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 30 V, f = 1 MHz                                       |     | 4700   |        | pF   |
| Output Capacitance                            | C <sub>oss</sub>            |  |     | 620    |        |      |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>            |  |     | 250    |        |      |
| Total Gate Charge <sup>c</sup>                | Qg                          |  |     | 78.5   | 120    | nC   |
| Gate-Source Charge <sup>c</sup>               | $Q_{gs}$                    | $V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$                             |     | 28     |        |      |
| Gate-Drain Charge <sup>c</sup>                | $Q_{gd}$                    |  |     | 20.6   |        |      |
| Gate Resistance                               | $R_{g}$                     | f = 1 MHz  |     | 1.2    | 2.4    | Ω    |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>          |  |     | 16     | 30     |      |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>              | $V_{DD}$ = 30 V, $R_L$ = 0.6 $\Omega$ $I_D$ $\cong$ 50 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$ |     | 10     | 20     | ns   |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>         |  |     | 25     | 40     |      |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>              |  |     | 8      | 15     |      |
| Source-Drain Diode Ratings and Cha            | racteristics T <sub>0</sub> | <sub>C</sub> = 25 °C <sup>b</sup>  |     | •      |        |      |
| Continuous Current                            | I <sub>S</sub>              |  |     |        | 85     | А    |
| Pulsed Current                                | I <sub>SM</sub>             |  |     |        | 240    |      |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>             | I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V   |     | 0.83   | 1.5    | V    |
| Reverse Recovery Time                         | t <sub>rr</sub>             |  |     | 62     | 100    | ns   |
| Peak Reverse Recovery Current                 | I <sub>RM(REC)</sub>        | $I_F = 75 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$                                |     | 3.8    | 5.7    | Α    |
| Reverse Recovery Charge                       | Q <sub>rr</sub>             |  |     | 118    | 180    | nC   |

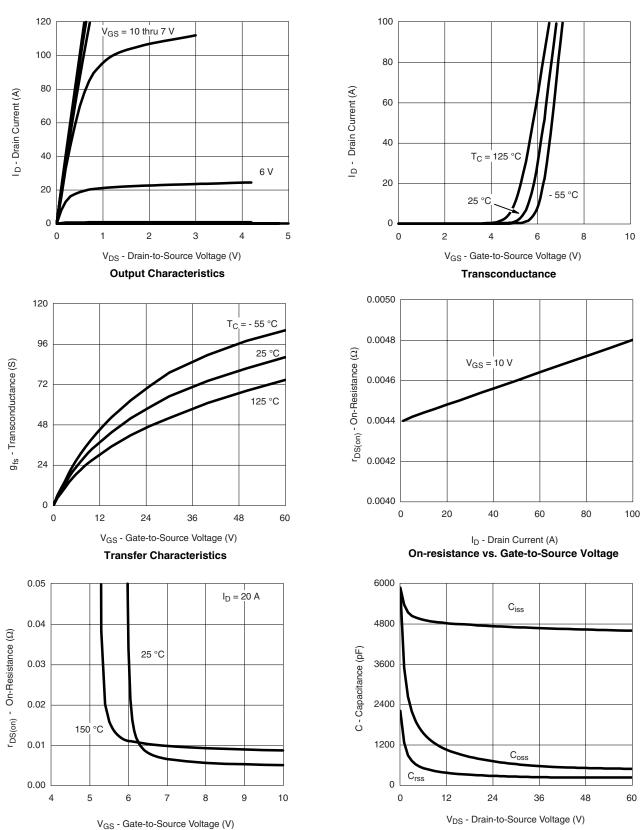
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



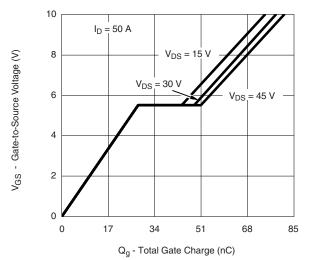
On-Resistance vs. Drain Current

Capacitance

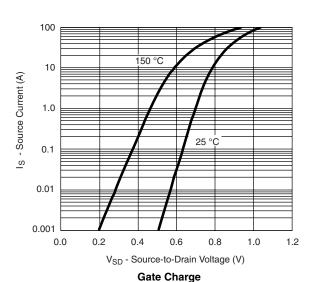
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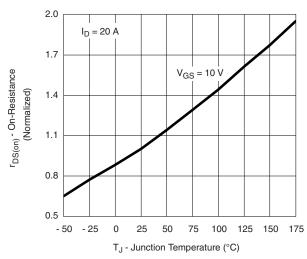
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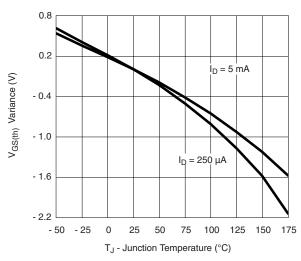
On-Resistance vs. Junction Temperature



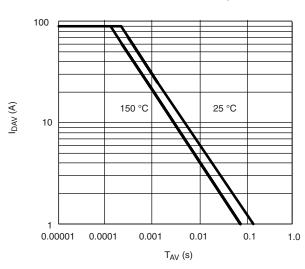
Source-Drain Diode Forward Voltage



Threshold Voltage



On-Resistance vs. Junction Temperature



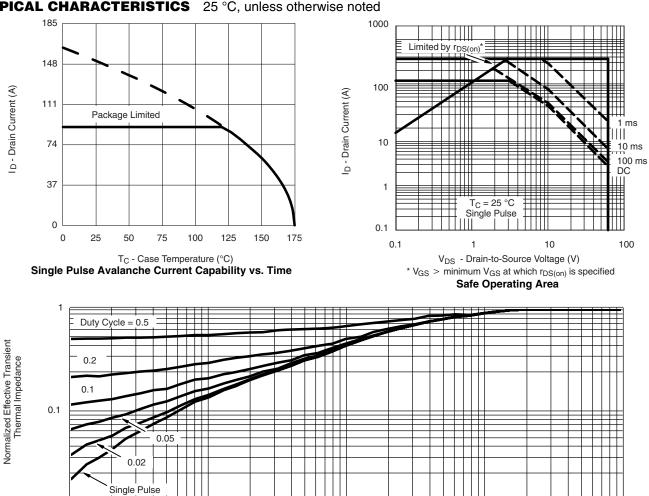
**Maximum Drain Current vs. Case Temperature** 



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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

10-3



Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Case

10-2

10<sup>-1</sup>

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